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		±	
	℃		
			℃

≠ ∧∃ Ã / Electrical Characteristics(Ta=25 ⊿)

≠ ∃ ̃Ạ´E ∀ ƒ / Electrical Characteristic Curve

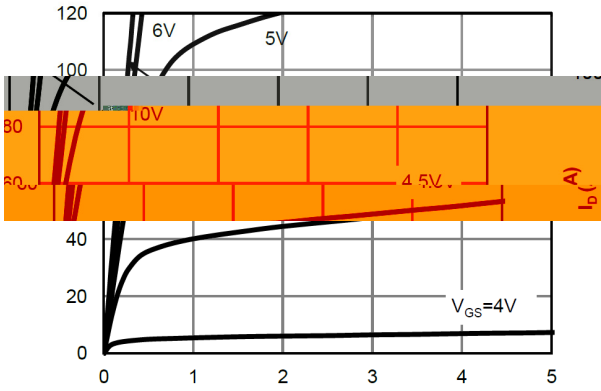

Figure 1: On-Region Characteristics

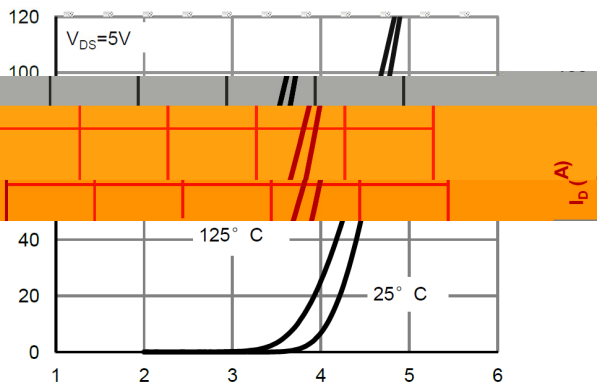

Figure 2: Transfer Characteristics

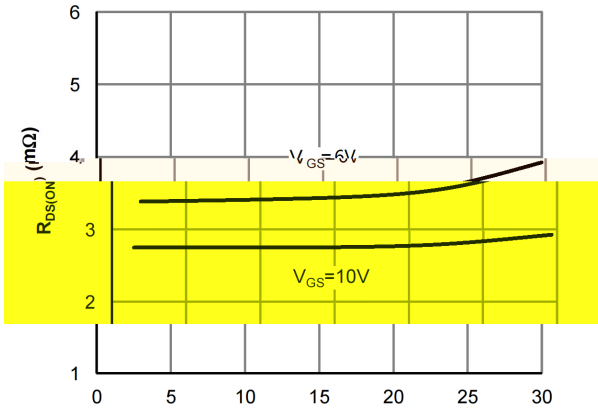

Figure 3: On-Resistance vs. Drain Current and Gate Voltage

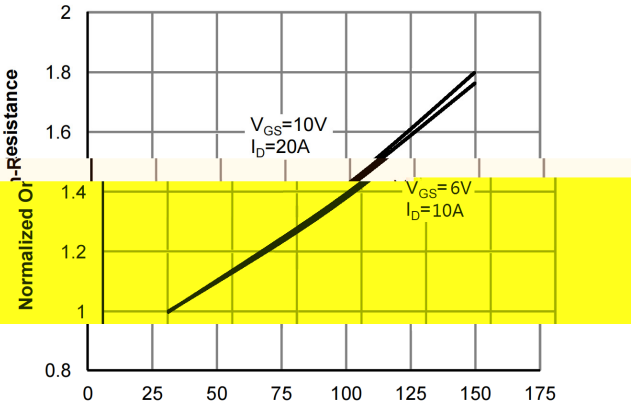

Figure 4: On-Resistance vs. Junction Temperature

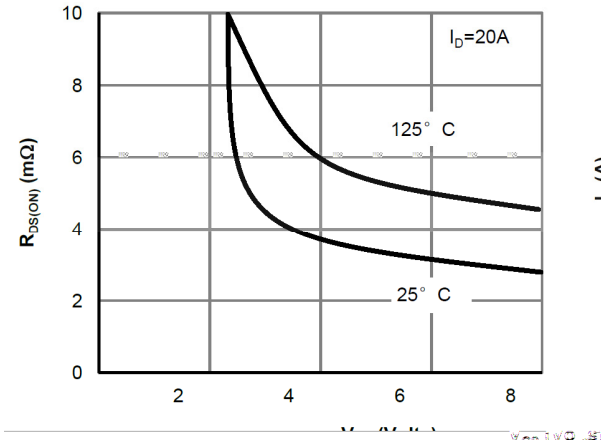

Figure 5: On-Resistance vs. Gate-Source Voltage

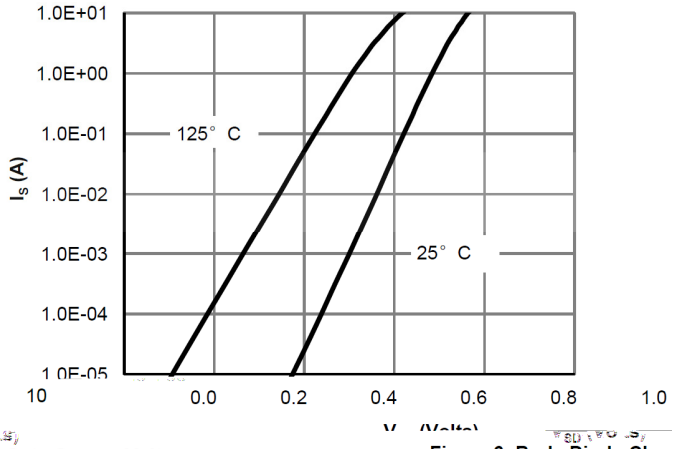

Figure 6: Body-Diode Char

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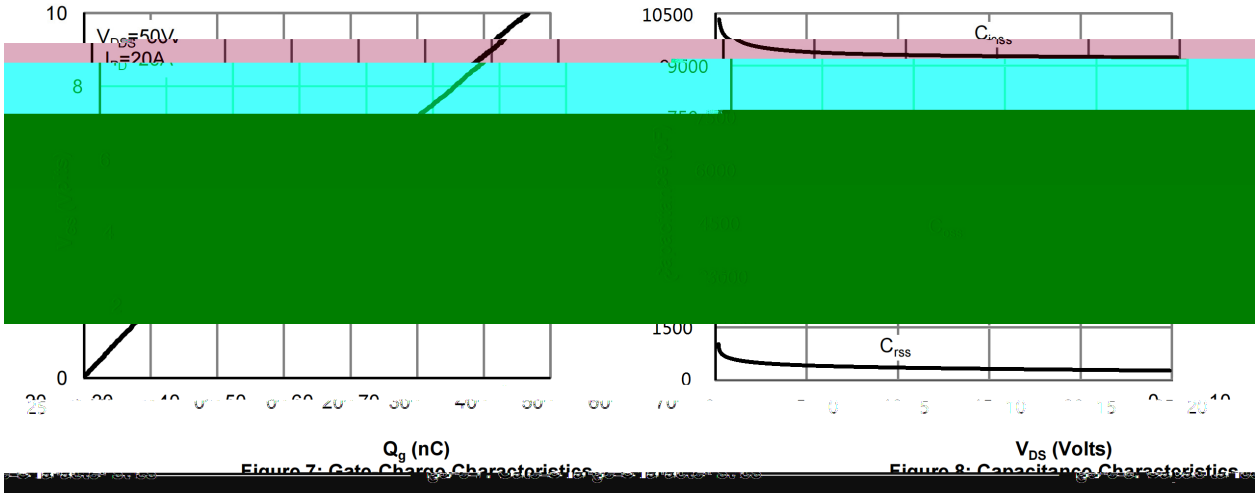


Figure 7: Gate Charge Characteristics

Figure 8: Capacitance Characteristics

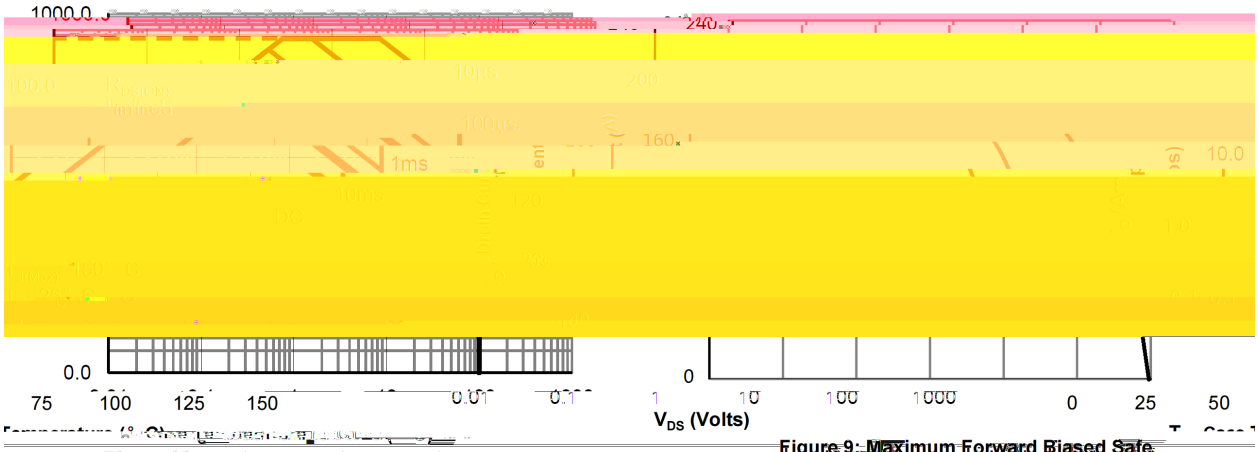
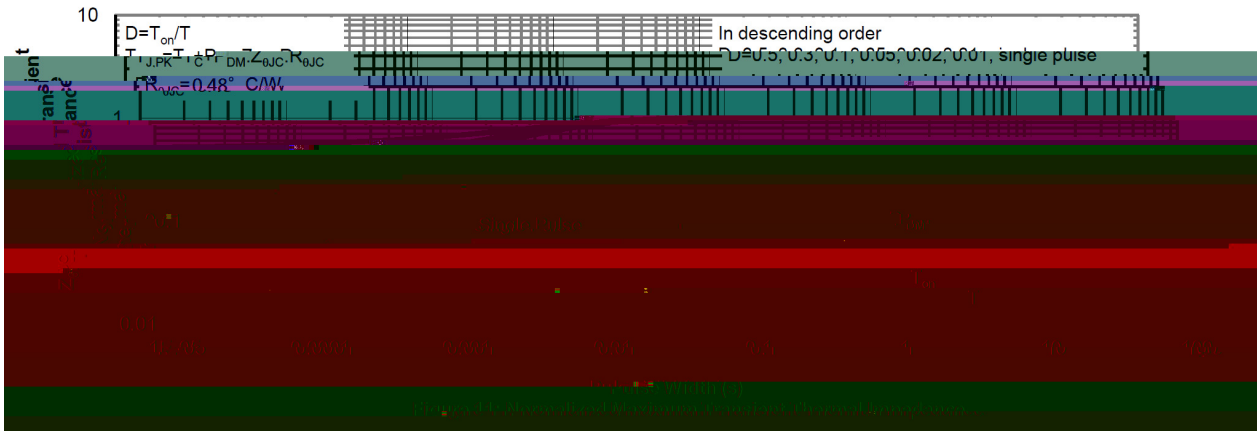


Figure 10: Maximum Continuous Drain Current vs Case Temperature

Figure 9: Maximum Forward Biased Safe Operating Area



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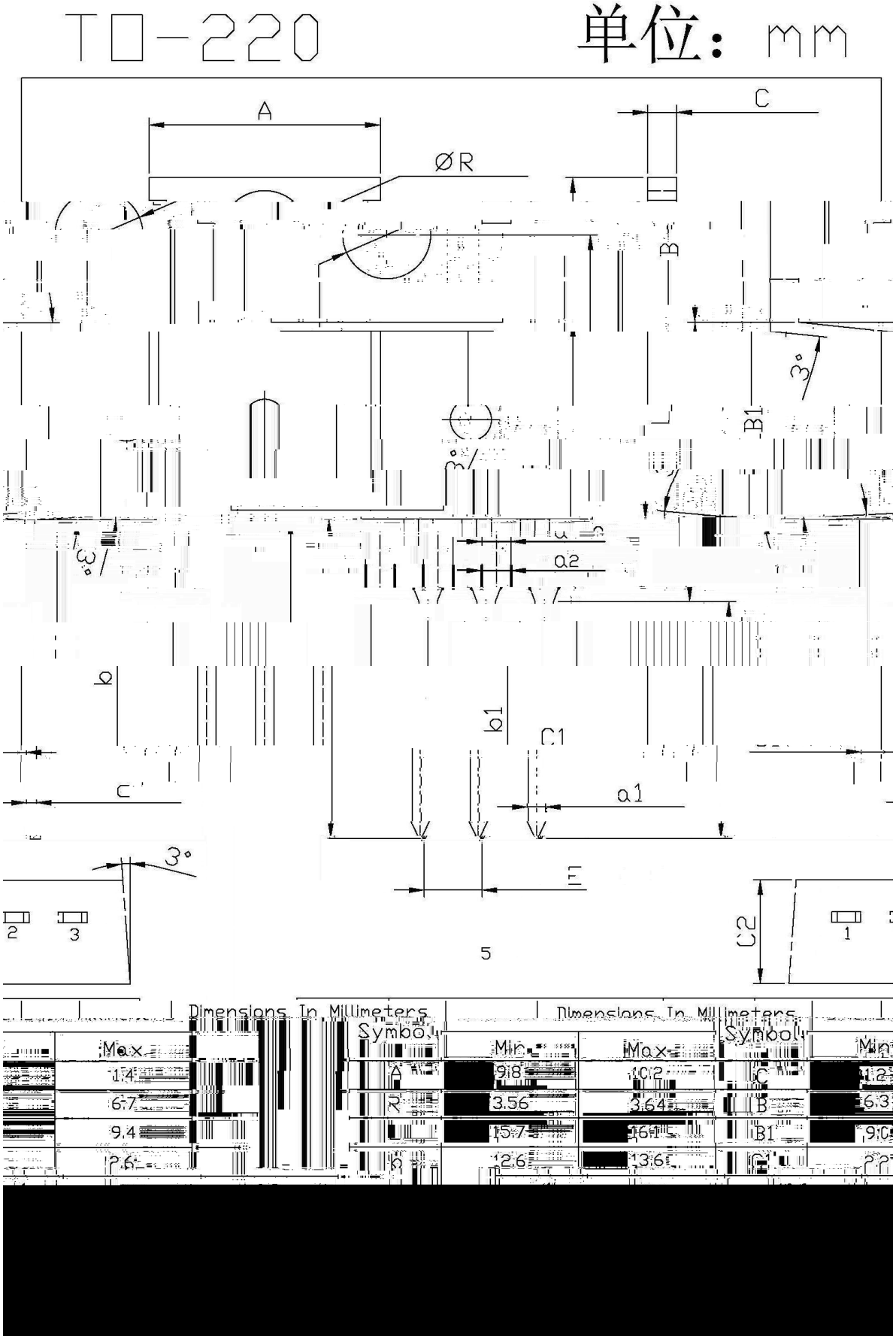
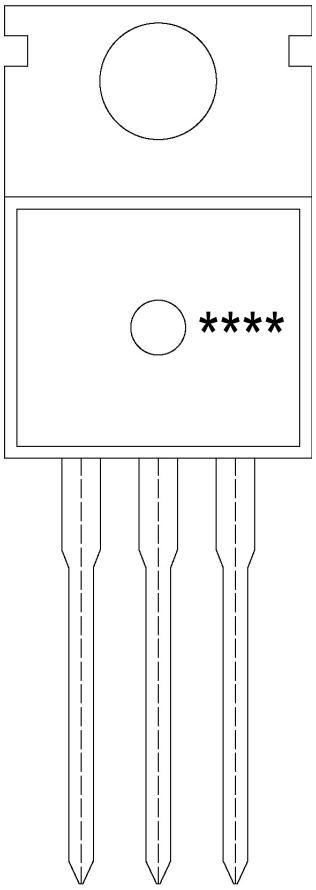


ł. Ļ Ω / Marking Instructions



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ɒ Ŀ ≮— / Packaging SPEC.

	Units/Bag /	Bags/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Bag	Inner Box	Outer Box
TO-220/F	200	10	2,000	5	10,000	135×190	237×172×102	560×245×195

	Units/Tube /	Tubes/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Tube	Inner Box	Outer Box
TO-220/F	50	20	1,000	5	5,000	532×31.4×5.5	555×164×50	575×290×180

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